

POLISHING METHOD, POLISHING COMPOSITION AND POLISHING
COMPOSITION KIT

ABSTRACT

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A polishing method for polishing a polysilicon film
provided on a silicon substrate having an isolation region is
provided. The method includes preliminarily polishing the
polysilicon film using a preliminary polishing composition
10 containing abrasive grains, an alkali, a water-soluble
polymer, and water till a part of the top surface of the
isolation region is exposed; and finally polishing the
preliminarily polished polysilicon film using a final
polishing composition containing abrasive grains, an alkali,
15 a water-soluble polymer, and water till the whole top surface
of the isolation region is exposed. The content of the
water-soluble polymer in the preliminary polishing
composition is 0.0075-0.05 % by mass, and the content of the
water-soluble polymer in the final polishing composition is
20 0.002-0.01 % by mass.

Fig. 1A